PATENT

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IN THE CLAIMS:

The following is a listing of all the claims as they currently stand. Claims 1-51 are canceled. Claims 52-74 are added as noted below.

1.-51. (Canceled)

52. (New) An in-line apparatus for creating an EMI shield, the apparatus comprising:

a conveyor assembly that moves a substrate;

a vacuum shaping assembly disposed at a first station, the vacuum shaping assembly comprising a vacuum source that pulls the substrate against a surface of a mold to shape the substrate into an EMI shield body, wherein the shaping assembly comprises a first portion disposed on a first side of the substrate and a second portion disposed on a second side of the substrate;

a metallization assembly at a second station that can create a seal around the shaped substrate, wherein the metallization assembly deposits a metal layer onto the shaped substrate; and

a cutting assembly disposed at a third station to cut the shaped substrate, the cutting assembly being movable relative to the shaped substrate.

53. (New) The in-line apparatus of claim 52 wherein the metallization assembly comprises:

a movable chamber configured to create a vacuum environment around a portion of the substrate;

a metal source and a thermal heat source that are spaced from the substrate and configured to deposit a metal layer onto the substrate in the vacuum environment,

wherein the movable chamber is movable between a first position adjacent the substrate and a second position apart from the substrate.

54. (New) The in-line apparatus of claim 53 wherein the conveyor assembly positions the substrate along a plane, wherein the metallization assembly is rotatable about an axis that is parallel to the plane of the substrate.

55. (New) The in-line apparatus of claim 52 wherein metallization assembly comprises a first and second metallization assembly on opposing sides of the substrate.

56. (New) The in-line apparatus of claim 52 wherein the metallization assembly is modular.

57. (New) The in-line apparatus of claim 52 wherein the metallization assembly comprises a filament and a metal source.

58. (New) The in-line apparatus of claim 52 wherein the metallization assembly is releasably coupled to a movable vacuum source.

59. (New) The in-line apparatus of claim 52 wherein the conveyor assembly positions at least a portion of the substrate along a plane, wherein the shaping assembly, metallization assembly and cutting assembly are movable orthogonal to the plane of the substrate.

60. (New) The in-line apparatus of claim 52 wherein the metallization assembly vacuum metallizes the shaped substrate.

61. (New) The in-line apparatus of claim 52 wherein the vacuum shaping assembly comprises a pre-heating element.

62. (New) The in-line apparatus of claim 52 further comprising an additional cutting station at a fourth station, wherein the fourth station is positioned before the metallization assembly at the second station.

63. (New) The in-line apparatus of claim 52 further comprising an additional cutting station at a fourth station, wherein the fourth station is positioned after the metallization assembly at the second station.

64. (New) An in-line apparatus for creating an EMI shield, the apparatus comprising:

a conveyor assembly that moves a substrate;

a vacuum shaping assembly disposed at a first station, the vacuum shaping assembly comprising a vacuum source that pulls the substrate against a surface of a mold to shape the substrate into an EMI shield body;

a metallization assembly at a second station that can create a seal around the shaped substrate, wherein the metallization assembly deposits a metal layer onto the shaped substrate; and

a cutting assembly disposed at a third station to cut the shaped substrate, the cutting assembly being movable relative to the shaped substrate,

wherein the conveyor assembly positions at least a portion of the substrate along a plane, wherein the shaping assembly, metallization assembly and cutting assembly are movable orthogonal to the plane of the substrate.

65. (New) The in-line apparatus of claim 64 wherein the metallization assembly comprises:

a movable chamber configured to create a vacuum environment around a portion of the substrate;

a metal source and a thermal heat source that are spaced from the substrate and configured to deposit a metal layer onto the substrate in the vacuum environment,

wherein the movable chamber is movable between a first position adjacent the substrate and a second position apart from the substrate.

66. (New) The in-line apparatus of claim 65 wherein the conveyor assembly positions the substrate along a plane, wherein the metallization assembly is rotatable about an axis that is parallel the plane of the substrate.

67. (New) The in-line apparatus of claim 64 wherein metallization assembly comprises a first and second metallization assembly on opposing sides of the substrate.

68. (New) The in-line apparatus of claim 64 wherein the metallization assembly is modular.

69. (New) The in-line apparatus of claim 64 wherein the metallization assembly comprises a filament and a metal source.

70. (New) The in-line apparatus of claim 64 wherein the metallization assembly is releasably coupled to a movable vacuum source.

71. (New) The in-line apparatus of claim 64 wherein the metallization assembly vacuum metallizes the shaped substrate.

72. (New) The in-line apparatus of claim 64 wherein the vacuum shaping assembly comprises a pre-heating element.

73. (New) The in-line apparatus of claim 64 further comprising an additional cutting station at a fourth station, wherein the fourth station is positioned before the metallization assembly at the second station.

74. (New) The in-line apparatus of claim 64 further comprising an additional cutting station at a fourth station, wherein the fourth station is positioned after the metallization assembly at the second station.